



# Product Change Notification

**Change Notification #:** 116649 - 00  
**Change Title:** Intel® Server System R2208WT2YSR, PCN 116649-00, Product Design, Hot-Swap Back Plane Firmware Update, PBA Riser change  
**Date of Publication:** December 18, 2018

## Key Characteristics of the Change:

Product Design

## Forecasted Key Milestones:

<b>Date Customer Must be Ready to Receive Post-Conversion Material *:</b>	January 2, 2019
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\* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

## Description of Change to the Customer:

Intel is updating the Hot-Swap Back Plane (HSBP) firmware from version 1.40 to 1.41 of the Intel Server Systems listed in the "Products Affected" table below. The firmware version 1.41 fixes a fault LED issue found on manufacturing.

The PBA (Product Board Assembly) of the Server Riser 3 "A2UX8X4RISER" has implemented SMBus support. The system must have installed the Integrated Baseboard Management Controller (BMC) firmware to revision 01.51.11142 or newer version to enable the SMBUs communication from new Riser 3.

The Riser 3 "A2UX8X4RISER" that is integrated on the Intel server System "R2208WT2YSR" rolled up the TA from G97701-004 to G97701-005. For details of this change consult the PCN 116513 - 00.

## Customer Impact of Change and Recommended Action:

Intel does not expect any other impact to customers from these changes, but encourages customers to understand the change and determine the impact on their applications. For that reason Intel recommends that the customer perform a standard level of evaluation. Customers can download and evaluate the latest BIOS/ME/Integrated BMC and FRUSDR release notes for more information at <http://www.intel.com/support>.

## Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre TA#	Post TA#
R2208WT2YSR	977055	J11485-011	J11485-012

## PCN Revision History:

<b>Date of Revision:</b>	<b>Revision Number:</b>	<b>Reason:</b>
December 18, 2018	00	Originally Published PCN



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**Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.**

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